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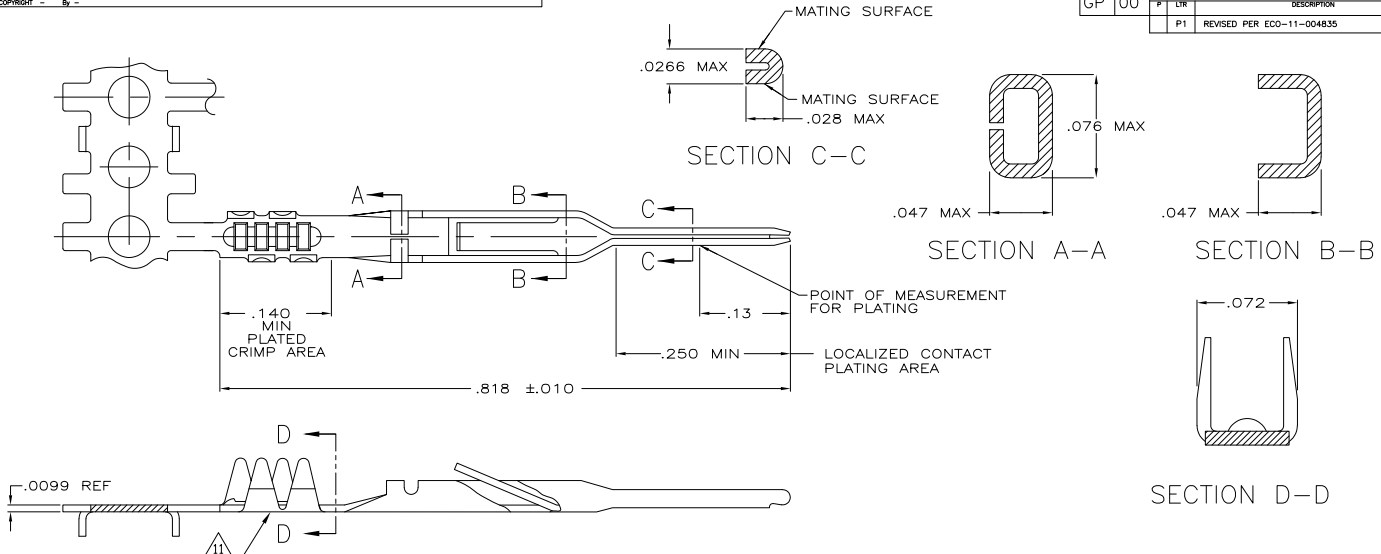
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LOC		DIBT		REVISIONS			DATE	MIN	APD
GP	00	P	LTR	DESCRIPTION			11MAR11	RK	HMR
		P1		REVISED PER ECO-11-004835					



- 1 NICKEL UNDERPLATE .000050 MIN THK ON ENTIRE CONTACT WITH GOLD .000050 THK ON LOCALIZED PLATE AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000050 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 2 NICKEL UNDERPLATE .000050 MIN THK ON ENTIRE CONTACT WITH GOLD .000015 THK ON LOCALIZED PLATE AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000015 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 3 NICKEL UNDERPLATE .000050 MIN THK ON ENTIRE CONTACT WITH GOLD .000030 THK ON LOCALIZED PLATE AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000030 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND BRIGHT TIN-LEAD .000100 MIN THK IN CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 4 BRIGHT TIN-LEAD .000100 MIN THK OVER NICKEL UNDERPLATE .000050 MIN THK ON ENTIRE CONTACT.
- 5 GOLD .000030 THK ON ENTIRE CONTACT, EXCEPT .000003 MIN THK PERMISSIBLE ON INTERIOR OF CONTACT NOSE, OVER NICKEL .000050 THK ON ENTIRE CONTACT.
- 6 GOLD FLASH IN PLATED CRIMP AREA, .000100 MIN TIN ON LOCALIZED CONTACT PLATING AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT.

- 7 .000050 MIN GOLD ON LOCALIZED PLATE AREA, GOLD FLASH IN PLATED CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000050 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND GOLD FLASH ON REMAINDER OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 8 .000015 MIN GOLD ON LOCALIZED PLATE AREA, GOLD FLASH IN PLATED CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000015 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND GOLD FLASH ON REMAINDER OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 9 .000030 MIN GOLD ON LOCALIZED PLATE AREA, GOLD FLASH IN PLATED CRIMP AREA, BOTH OVER .000050 MIN NICKEL ON ENTIRE CONTACT, -OR- GOLD FLASH OVER PALLADIUM-NICKEL, .000030 MIN TOTAL THK IN LOCALIZED CONTACT PLATING AREA AND GOLD FLASH ON REMAINDER OVER .000050 MIN NICKEL ON ENTIRE CONTACT.
- 10 OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
- 11 GOLD PLATING MAY OR MAY NOT BE PRESENT ON THE BOTTOM OF THE CRIMP BARREL.

1-88117-0	1-88117-9	88117-8	88117-7	88117-6	88117-5	88117-4	88117-3	88117-2
		OBSOLETE	OBSOLETE	OBSOLETE				OBSOLETE
								FNSH PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT. DIM: P. BERRY 3-21-06. CHK: D. S. WORTHINGTON 2-24-06. APPG: -- NAME: -- PRODUCT SPEC: -- APPLICATION SPEC: 114-16015. WEIGHT: -- SIZE: A2. CASE CODE: 00779. DRAWING NO: C-88117. CUSTOMER DRAWING. SCALE: NTS. SHEET: 1 of 1. REV: P1.

TE Connectivity CONTACT, .025 SQ PIN

1471-9 (3/11)